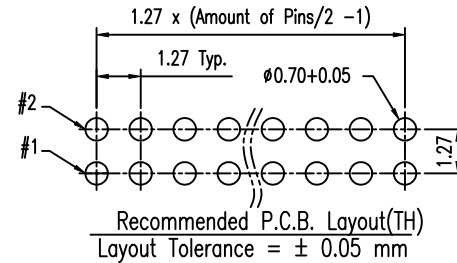


NOTE:

- MATERIAL:  
HOUSING: HIGH TEMP THERMAL PLASTIC, UL94-V0  
TERMINAL: COPPER ALLOY
  - FINISH:  
TERMINAL: GOLD AT CONTACT,  
G/F OVER  $1\mu\text{M}(40\mu'')$  MIN NI OVER ALL
  - SPEC.:  
PRODUCT SPEC: GS-12-629  
PACKING SPEC: GS-14-1517
  - THE HSG. WILL WITHSTAND EXPOSURE TO 260C PEAK TEMP. FOR 10 SEC. IN A WAVE SOLDER APPLICATION.
  - MATING SIDE LENGTH: 2.5MM MIN.
  - PRODUCT NUMBERING:  
200218 1 3 - XXX XX X X LF
- LEAD FREE  
PLATING:  
1: G/F ALL OVER  
4:  $0.25\mu\text{M}(10\mu'')$  GOLD AT CONTACT  
8:  $0.76\mu\text{M}(30\mu'')$  GOLD AT CONTACT  
PACKING  
T: TUBE  
PIN COUNT  
04, 06, 08, ..., 98, A0  
( EVERY EVEN PIN )  
STACK HEIGHT "K"  
EXAMPLE: 045=4.5MM  
IN 0.5MM INCREMENT



mat'l. code		surface <input checked="" type="checkbox"/> tolerance		projection	product family 585
ltr	ecn no	dr	date	tolerances unless otherwise specified	
A	T10-0188	S.LIN	10'-10-05	 MM	title 1.27X1.27MM BTB STACK HD VT, TH
angled		lead	.X $\pm$ 0.38		
0 $\pm$ 2'		line	.XX $\pm$ 0.25		
			.XXX $\pm$ 0.10	scale N/A	
dr	STERLING LIN		10'-12-21		sheet 1 of 1 size 20021813 A4
eng	STERLING LIN		10'-12-21		
chr	STERLING LIN		10'-12-21		
app	GARY HSIEH		10'-12-21		
sheet index	revision A	sheet	1	type	CUSTOMER Drawing